



Tapes for electronics and industrial applications

Converting services

Who we are



We employ 140 people



4 locations – a total of 5000 m²



wide range of materials and components of well-known world brands



innovative services, modern production lines

Laser plotter CO₂
Cutting head with oscillating knife



The flat-bed die-cutting machine



Member of

- Polish Space Industry Association
- Polish Technological Platform on Photonics
- Polish Chamber of Commerce for Electronics and Telecommunications
- Microelectronics, Electronics & Photonics Cluster



space.biz.pl



pptf.pl

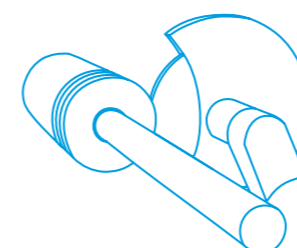


kiget.org.pl



Microelectronics, Electronics & Photonics Cluster

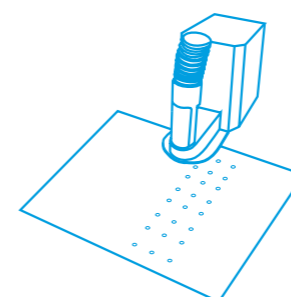
Our services – converting:



Cutting saw

Log roll Slitting

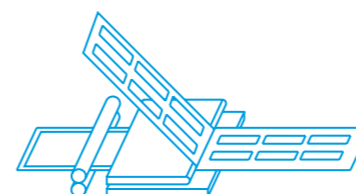
- Maximum length of log roll: 1700 mm
- Minimum tape width: 6 mm
- Cutting accuracy: 0,1 mm
- Maximum diameter of log roll: 430 mm



Laser plotter – oscillating knife cutter

Cutting out

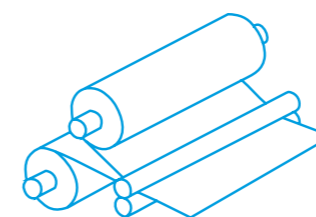
- Working area 1330 mm x 830 mm
- Cutting demanding materials
- Cutting adhesive transfer tapes
- Cutting foams and other materials
- Filtering fume extractor



Tact press

Matrix cutting die: Die-Cut and Kiss-Cut

- Materials with thickness of 0,05 mm to 10 mm
- Working area 300 mm x 300 mm



Laminator

Laminating

- Operating width up to 1600 mm

Slitting log rolls and industrial velcros

We cut using:

- Specialist machine with a cuvisc

Technology and materials

The machine enables slitting log rolls (large roll of thin foil, often with a layer of glue) up to 1700 mm long. It is equipped with a PLC controller from Siemens to adjust the speed of the cutting disc. The machine features a built-in disc sharpening and cooling system, a disc wetting system, and a roller pressure system for converting metal foils with no deformation of edges. It ensures high repeatability and smooth cutting line of:

- Tapes, including types with aggressive, strong glue
- Copper and aluminium foils
- Adhesive transfer tapes
- Velcros



Cut-outs – laser plotter

We make cut-outs using:

- A plotter cutter with a CO₂ laser head
- A plotter cutter with a head featuring an oscillating knife cutter

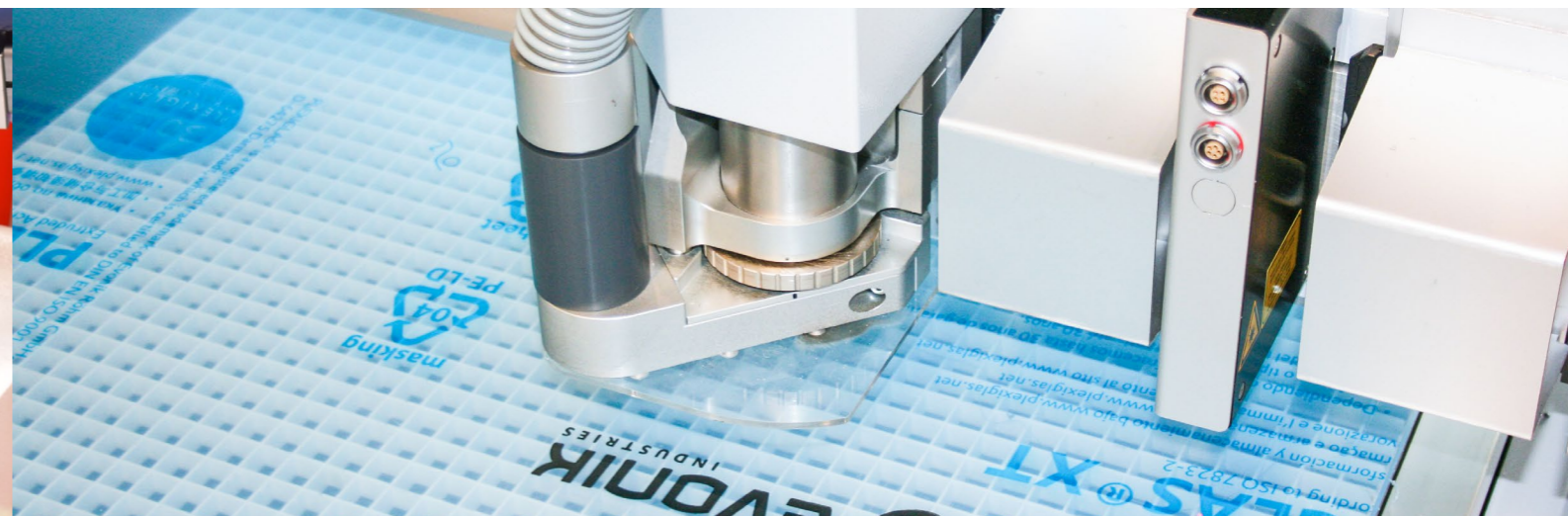
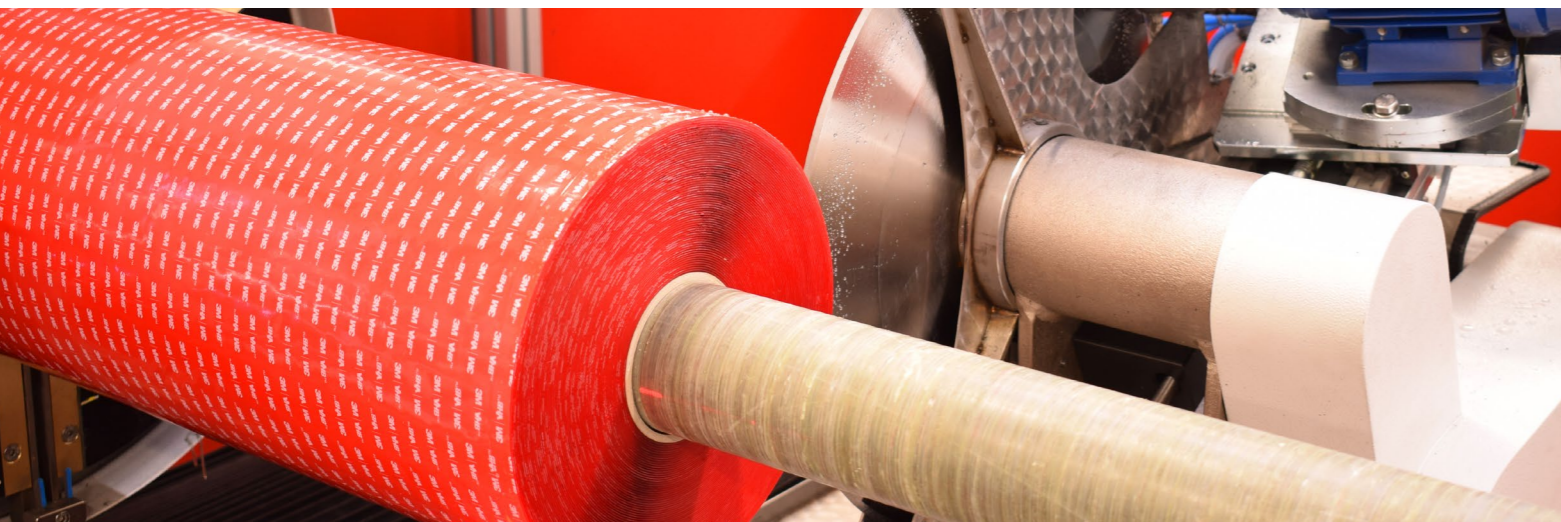
Technology

- The plotter cutter includes a 1330 x 830 mm working table. Depending on the material cut, we use a CO₂ laser head or head featuring an oscillating knife cutter.
- Using CAD software means that there's not need to prepare dies in advance, which significantly speeds-up the production process.

Materials

The machine enables precise cutting of demanding materials, such as:

- Foams
- Adhesive transfer tapes
- Thin VHB tapes
- Poured acrylic
- Plastics
- Cloths
- Foils
- Plywood
- Composites



Cut-outs – mechanical die

For Die-Cut and Kiss-Cut we use:

- 10t tact press

Technology and materials

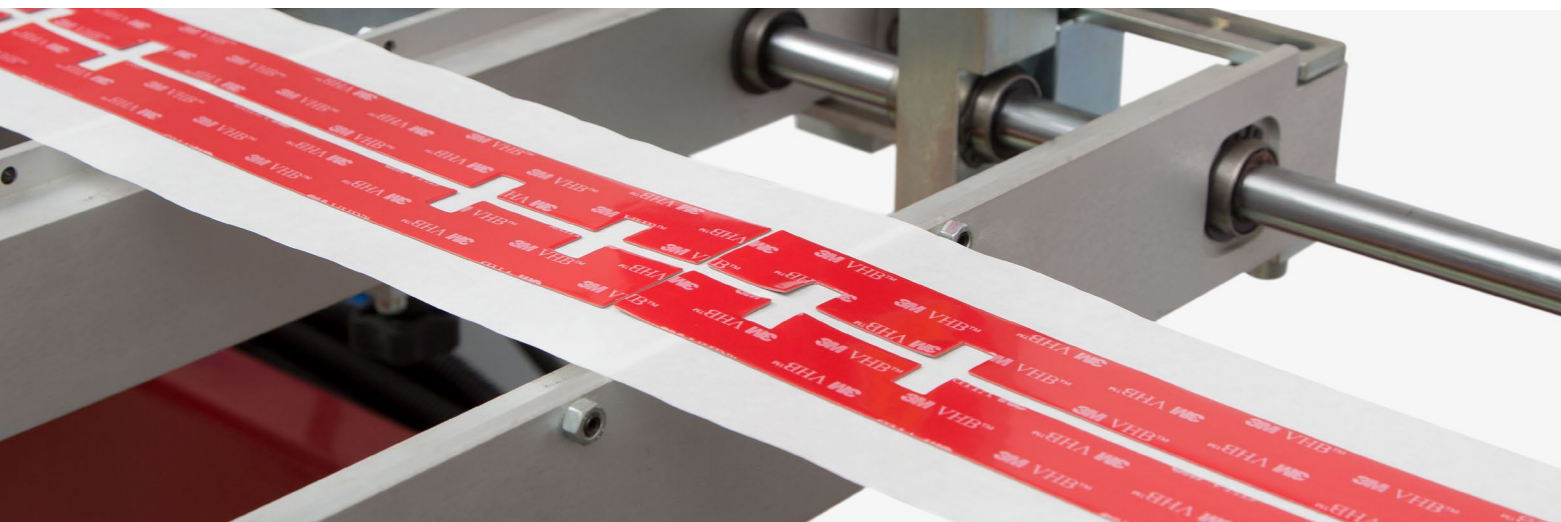
The press enables:

- Die-Cut
 - Cutting-out a shape from the die in the tape with liner cutting
- Kiss-Cut
 - Cutting-out a shape from the die in the tape while leaving the liner intact

The machine can be programmed to cut out a shape with a finger lift, i.e. an additional part that makes it easier to remove the liner from the adhesive side.

The device supports material converting in the following configurations:

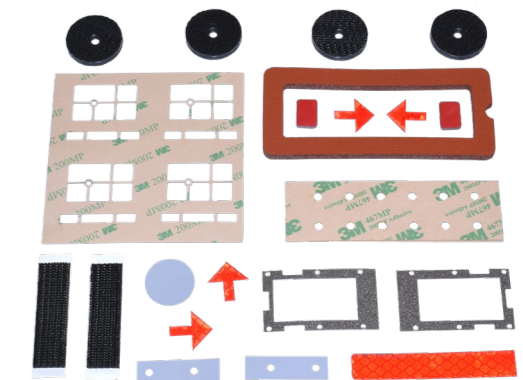
- Die-Cut + Kiss-Cut
- Die-Cut and Kiss-Cut



Converted materials

Tapes

- Thermally conductive
- Polyimide (kapton)
- Electrical (insulating)
- Corrosion Protection
- Self-amalgamating
- Polyester
- Shielding
- VHB, acrylic
- Erosion protection PPT (Polyurethane Protective Tape)
- Aluminium foil
- Copper foil
- Foam
- Cloth surgical tapes
- Epoxy
- Masking
- Protective foil



Materials reinforced with glass fibre

Velcros

Foams

Adhesive transfer tapes for lamination

- Acrylic
- Silicone
- Double sided silicone acrylic
- Electrically conductive



Our suppliers:





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WARSAW

- Headquarters and R&D department
- Electronic Manufacturing Services
- SMT Laser cut stencils manufacturing
- Main warehouse

